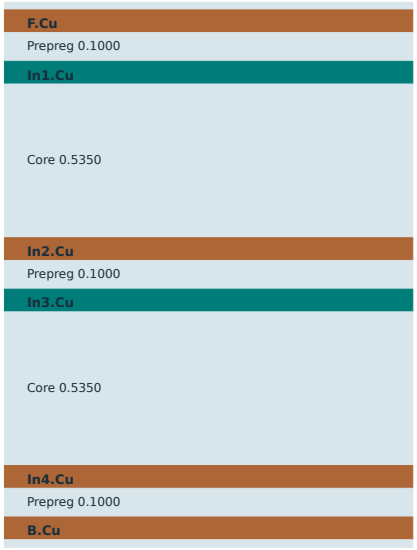
Stackup & fabrication

Saved laminate definition, copper allocation and through-via inventory

6 COPPER LAYERS

Thickness exaggerated



Layer	Material	t (mm)	Er	Df	Saved role
F.Mask	Mask	0.01	—	—	Coating
F.Cu	Copper	0.035	—	—	Signals / power
dielectric 1	FR4	0.1	4.5	0.02	Insulation
In1.Cu	Copper	0.035	—	—	GND reference
dielectric 2	FR4	0.535	4.5	0.02	Insulation
In2.Cu	Copper	0.035	—	—	Signals / power
dielectric 3	FR4	0.1	4.5	0.02	Insulation
In3.Cu	Copper	0.035	—	—	GND reference
dielectric 4	FR4	0.535	4.5	0.02	Insulation
In4.Cu	Copper	0.035	—	—	Signals / power
dielectric 5	FR4	0.1	4.5	0.02	Insulation
B.Cu	Copper	0.035	—	—	GND label; signal routing
B.Mask	Mask	0.01	—	—	Coating

Thickness sum: 1.600 mm with masks; 1.580 mm without masks.

FR4: Er 4.5 / Df 0.02. All copper layers: 0.035 mm.

Saved finish: None. No specific laminate or impedance target.

THROUGH VIAS

Land Ø	Drill Ø	Annulus	Count
0.45	0.2	0.125	767

In1 and In3 are ground references. B.Cu is named GND but also carries signals; inspect copper and return paths. Confirm stack, finish and drill capability before fabrication.

767 routing vias. Component and mounting drills are separate.

Dennis, Ranko, Renee / Minimig.ca / Precision-Arrays

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Units: mm. Saved CAD governs. 3D views are illustrative.

A4 landscape. Print at 100% for the stated drawing scales.